



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Chia-Chung Wang et al.  
Assignee: Bridge Semiconductor Corporation  
Title: METHOD OF MAKING A SEMICONDUCTOR CHIP ASSEMBLY WITH A CONDUCTIVE TRACE AND A SUBSTRATE  
Serial No.: 10/646,415 Filed: August 22, 2003  
Examiner: Dang, P. Group Art Unit: 2818  
Atty. Docket No.: BDG018

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COMMISSIONER FOR PATENTS  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT AFTER ALLOWANCE**

Please amend the application as follows.

The Specification Amendments begin at page 2.

The Remarks begin at page 3.